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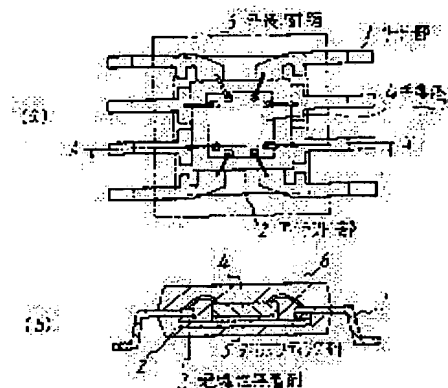
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To improve the reliability in moisture resistance, heat dissipating properties and manufacturing yield, by using a lead frame in which different materials are joined together by means of an insulating adhesive.

CONSTITUTION: Leads 1 constituting a lead frame is formed of 42 alloy having a linear expansion coefficient lower than that of a molding material or sheathing resin. An island 2 is formed of a Cu alloy having thermal conductivity lower than that of the leads. The leads 1 are bonded to the island 2 by means of an insulating adhesive 3 comprising tape composed basically of polyimide on which an epoxy adhesive agent is applied, and a lead frame is constituted thereby. Following to mounting a semiconductor chip 4 on the island 2 by means of a die bonding agent 5, electrode pads of the semiconductor chip 4 are connected to the leads 1 by bonding them and the lead frame and the semiconductor chip 4, except the tip ends of the leads 1 which should be left exposed, are covered with and molded with a sheathing resin 6.



LEGAL STATUS

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